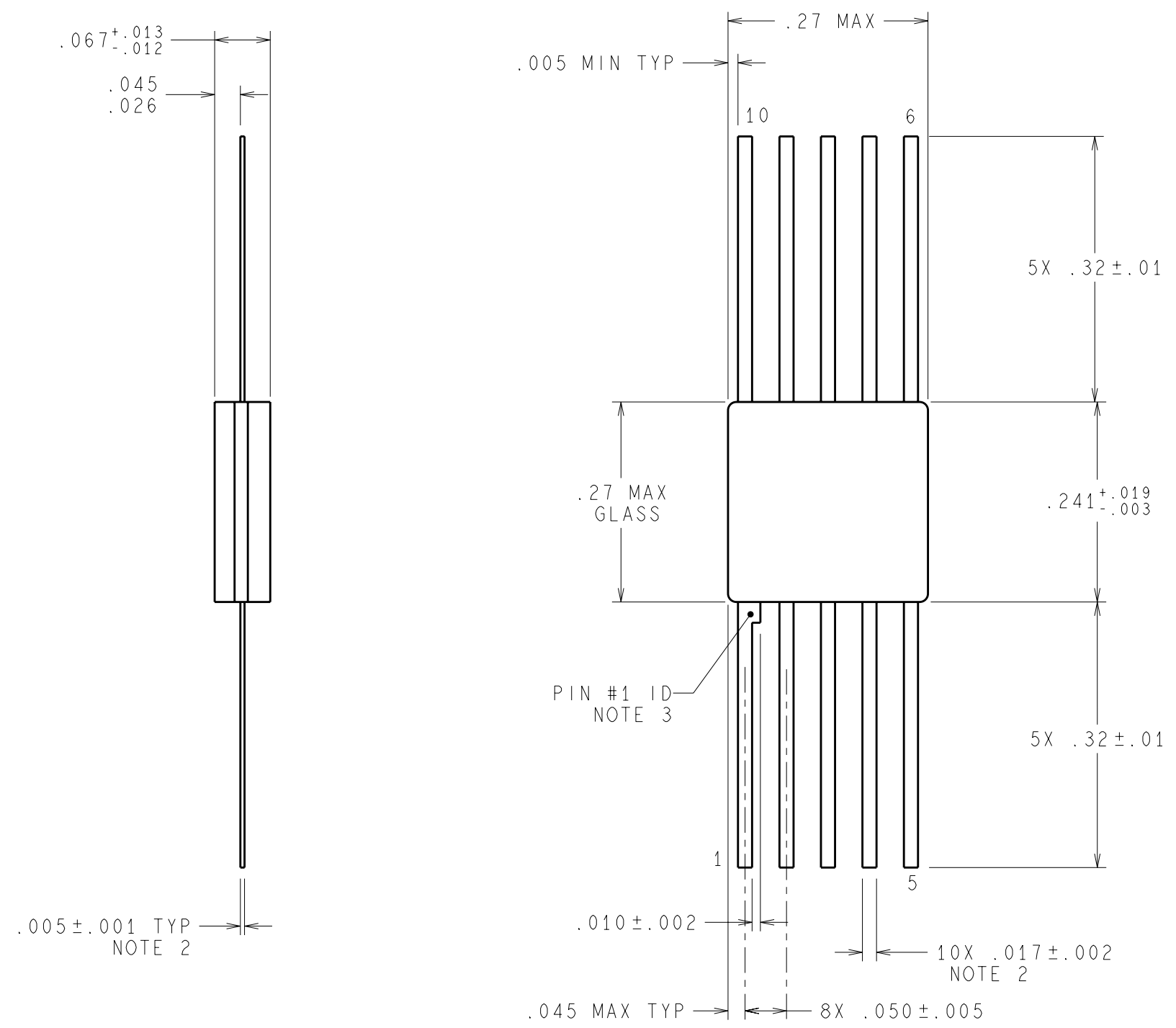


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
F	REVISE AND REDRAW PER NEW STANDARD.	10510	07/28/1994	DEG/AEP
G	.017±.002 WAS .017±.020.	10654	10/21/1994	DEG/CD
H	DIM .045/.026 WAS .031±.004/-.005; REVISE NOTE 1; UPDATE NOTE 4, MIL/AERO STAMPS & TITLE.; CHANGE DWG FORMAT TO B SIZE.	1162	09/08/2003	MS/SWK



DIMENSIONS ARE IN INCHES

MIL-STD-1835B  
CONFIGURATION CONTROL

MIL-PRF-38535  
CONFIGURATION CONTROL

NOTES: UNLESS OTHERWISE SPECIFIED

- FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE ([www.national.com](http://www.national.com)).
- MAXIMUM LIMIT MAY BE INCREASED BY .003 INCHES AFTER LEAD FINISH APPLIED.
- LEAD 1 IDENTIFICATION SHALL BE:
  - A NOTCH OR OTHER MARK WITHIN THIS AREA.
  - A TAB ON LEAD 1, EITHER SIDE.
- REFERENCE JEDEC REGISTRATION MS-033, VARIATION AA.

APPROVALS	DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DRAWN DE Grady	07/28/1994			
DTG. CHK. THANH LEQUANG	09/08/2003			
ENGR. CHK. SHARE WING KO	09/08/2003			
<b>CERPACK, .270 X .241 X .067 BODY, 10 LD, .050 PITCH</b>				
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
	NTS	B	(SC)MKT-W10A	H
FORMERLY: N/A		SHEET 1 of 1		